

SOT1190-1

plastic low profile fine-pitch ball grid array package; 144 balls,
0.8 mm pitch, 10 mm x 10 mm x 1 mm body

11 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA144
Package type industry code	LFBGA144
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	10-01-2013
Manufacturer package code	SOT1190

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	9.9	10	10.1	mm
seated height	1.25	1.35	1.5	mm
package height	0.95	1	1.1	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	144	-	



2 Package outline

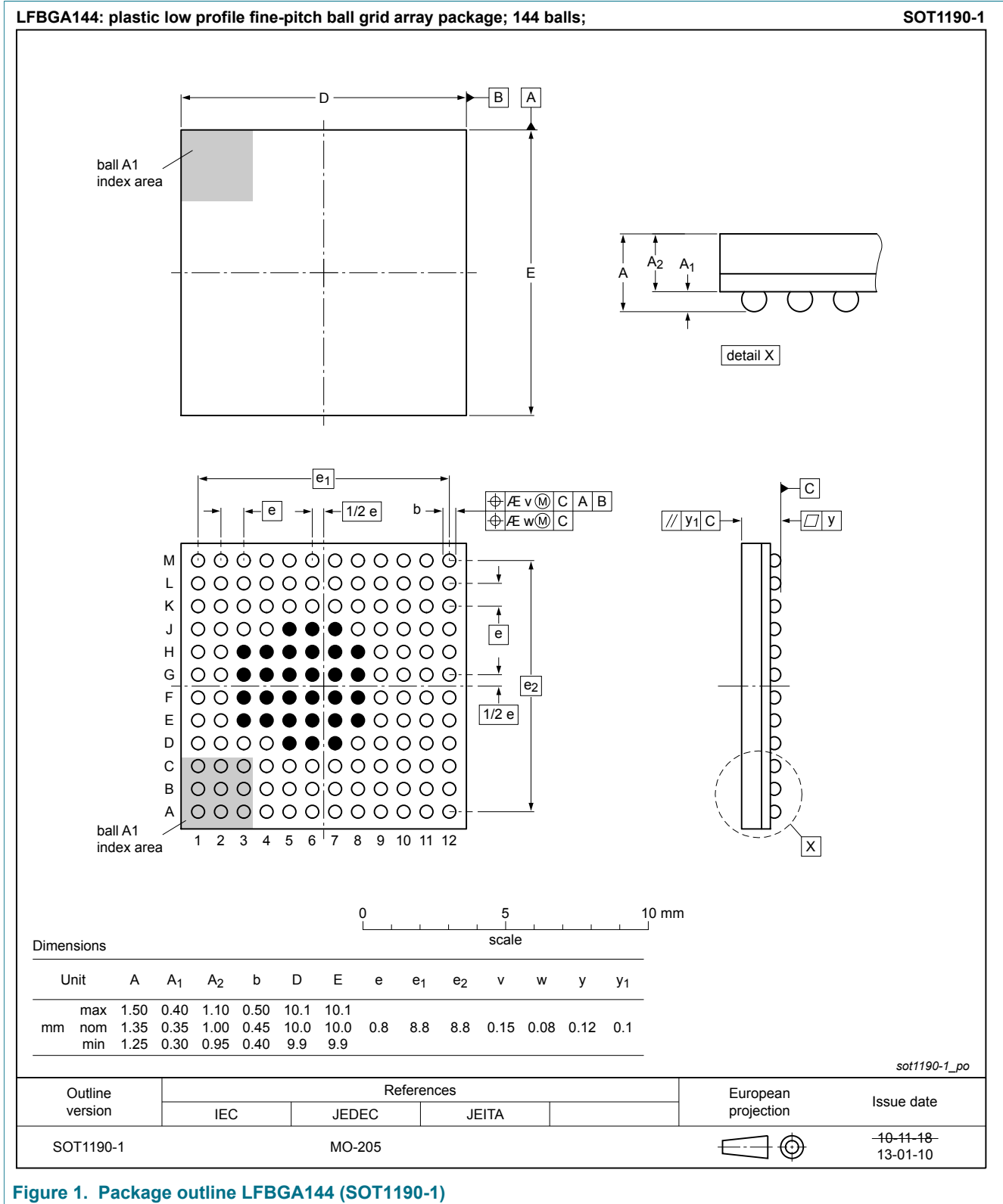


Figure 1. Package outline LFBGA144 (SOT1190-1)

3 Legal information

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